

Waffles Anyone?

Waffle tip bonding tools are used in the semiconductor industry mainly for ribbon and "lead to lead" bonding applications. Waffle tip tools provide several advantages in these applications:

Improved Heat Dissipation: The waffle tip design enables better heat dissipation during the wire bonding process.

Reduced Damage: The waffle tip design distributes the pressure more evenly, reducing the risk of damaging delicate components or substrates during the bonding process.

Longevity: The design of waffle tips can often contribute to a longer lifespan for the bonding tool due to the more even distribution of wear and tear.

Versatility: Waffle tip bonding tools can often accommodate a range of wire diameters and materials, making them versatile for various bonding applications.

Quality of Bonds: The design of the waffle tip can lead to improved bond quality, ensuring reliable and consistent connections.

Micro Point Pro Ltd (MPP) offers a wide range of waffle tools made of a variety of materials including: Tungsten carbide (WC), Titanium (TiC) carbide and special Ceramic compositions. Our tools are made with the most advanced manufacturing techniques to guarantee best in class quality and consistency.

